

8 GHz ft Wideband PNP Chip – BFT977

Silicon PNP Planar RF Transistor in bare die form

Rev 1.0 17/6/25

Description

PNP transistor in unencapsulated chip form. It is primarily intended for use in RF wideband amplifiers, such as in aerial amplifiers, radar systems, oscilloscopes, spectrum analyzers, etc. The transistor features low intermodulation distortion and high power gain; due to its very high transition frequency, it also has excellent wideband properties and low noise up to high frequencies. The device provides equivalent or higher performance than legacy transistors such as BFT92, BFT93, NE97833 or NE97733. Closest available NPN complement is 2SC3356.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-750 /2072 Visual Inspection
- "H" MIL-STD-750 /2072 Visual Inspection+ MIL-PRF-38534 Class H LAT
- "K" MIL-STD-750 /2072 Visual Inspection+ MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

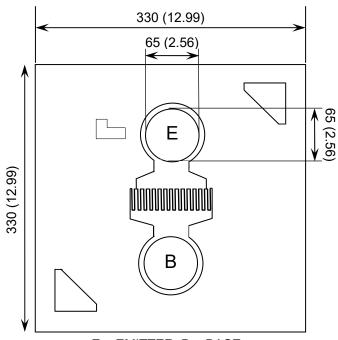
Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape By specific request
- Unsawn Wafer By specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

Features:

- High Power Gain
- Low Noise
- Wide Transition Frequency

Die Dimensions in µm (mils)



E = EMITTER, B = BASE CHIP BACKSIDE IS COLLECTOR

Mechanical Specification

Die Size (Unsawn)	330 x 330 12.99 x 12.99	μm mils	
Base & Emitter Bond Pad Size	65 Ø 2.56 Ø	µm mils	
Die Thickness	180 (±10) 7.09 (±0.39)	µm mils	
Top Metal Composition	Al		
Back Metal Composition	Au 1μm		





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Absolute Maximum Ratings T_A = 25°C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V _{CBO}	Collector-Base Voltage	Open Emitter	-	-20	V
V _{CEO}	Collector-Emitter Voltage	Open Base	-	-12	V
V _{EBO}	Emitter-Base Voltage	Open Collector	-	-3	V
I _C	DC Collector Current	-	-	-50	mA
P _{tot}	Total Power Dissipation	-	-	200	mW
T _{stg}	Storage Temperature	-	-65	150	°C
T _J	Junction Temperature	-	-	150	°C
R _{TH (J-C)}	Thermal Resistance (Junction to Case)	Assembled in Micro-X Package	-	85	-

Electrical Characteristics T_A = 25°C

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	SYMBOL
I _{CBO}	Collector Cut-off Current	I _E = 0 ; V _{CB} = -10V	-	-	-0.1	μA
I _{EBO}	Emitter Cut-off Current	$I_{C} = 0$; $V_{EB} = -1V$	_	_	-0.1	μA
h _{FE}	DC Current Gain	$I_C = -20 \text{mA}; V_{CE} = -8 \text{V}$	50	-	210	-
f _T	Transition Frequency	$I_C = -20mA; V_{CE} = -8V;$ f = 1 GHz	6	8	-	GHz
S _{21e} ²	Insertion Power Gain	$I_C = -20 \text{mA}; V_{CE} = -8V;$ f = 1 GHz	_	12	-	dB
NF	Noise Figure	I_{C} = -3mA; V_{CE} = -8V; f = 1 GHz	_	1.5	-	dB
C _{re}	Feedback Capacitance	$I_{C} = -20 \text{mA}; V_{CE} = -8V$ f = 1 MHz	-	0.5	1	pF

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